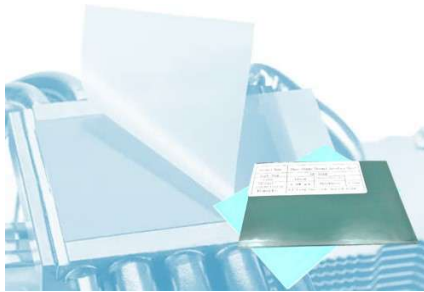


Phase Change Thermal Pad



Features:

1. Solid at room temperature with natural tacky properties for easy assembly, melts and softens at 45~55°C, offering good wet-out properties and low thermal impedance.
2. Optional PI film or Aluminum Foil substrate (high electrical insulation performance: SP350P).

Applications:

Filling gaps between CPU/GPU and heatsinks.

Model	Color	Thermal Conductivity W/m·K	Thermal Impedance, °C*in ² /W at 20psi, 1mm	Custom Thickness, mm	Phase Change Temp., °C	Operating Temp., °C
JSSP-205A-30	Gray	3.0	0.05	0.13~0.5	45~55	-40~125
JSSP-205A-35	Gray	3.5	0.04	0.13~0.5	45~55	-40~125
JSSP-205A-40	Gray	4.0	0.03	0.2~0.5	45~55	-40~125
JSSP-205A-50	Gray	5.0	0.02	0.2~0.5	55~65	-40~125
JSSP-205A-60	Gray	6.0	0.015	0.2~0.5	45~55	-40~125
JSSP-205A-L80	Gray	8.0	0.007	0.2~0.5	45~55	-20~100
JSSP-350P	Green	1.8	0.4	0.2~0.5	45~55	-20~120